

Application Serial No. 10/811,511
Reply to Office Action of November 14, 2006

PATENT
Docket: CU-3665

REMARKS

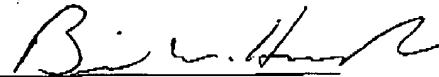
In the Office Action, dated November 14, 2006, the Examiner states that Claims 6-10 are pending, and Claims 6-10 are rejected. By the present Amendment, Applicant amends the claims.

In the Office Action, Claims 6-10 are rejected under 35 U.S.C. §102(a)/§103(a) as being anticipated by/obvious over Dontula et al. (US 6,514,659). The Applicant considers that the amendment to independent Claim 6 overcomes this rejection.

Claim 6 as amended indicates that the base material sheet and the base material film are bonded together without using an adhesive, via a molten resin while extrusion-molding the resin. The bond is established by utilizing the nature/state of the heated molten resin while it is extruded-molded. This simplifies the manufacturing process, and is not taught by the cited prior art. Thus, the Applicant considers that the amendment overcomes the rejection.

In light of the foregoing response, all the outstanding objections and rejections are considered overcome. Applicant respectfully submits that this application should now be in condition for allowance and respectfully requests favorable consideration.

Respectfully submitted,



February 14, 2007

Date

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